SPECIFICATION

COMMERCIALLY AVAILABLE

SAW BAND PASS
PART NUMBER:SF0800135
RoHS

ISSUED / REVISION	ENGINEER APPROVED	DOCUMENT CHECKED	DRAFTSMAN
2/29/16 (kn)			

***FILTRO**NETICS Inc*

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***FILTRO**NETICS, Inc*
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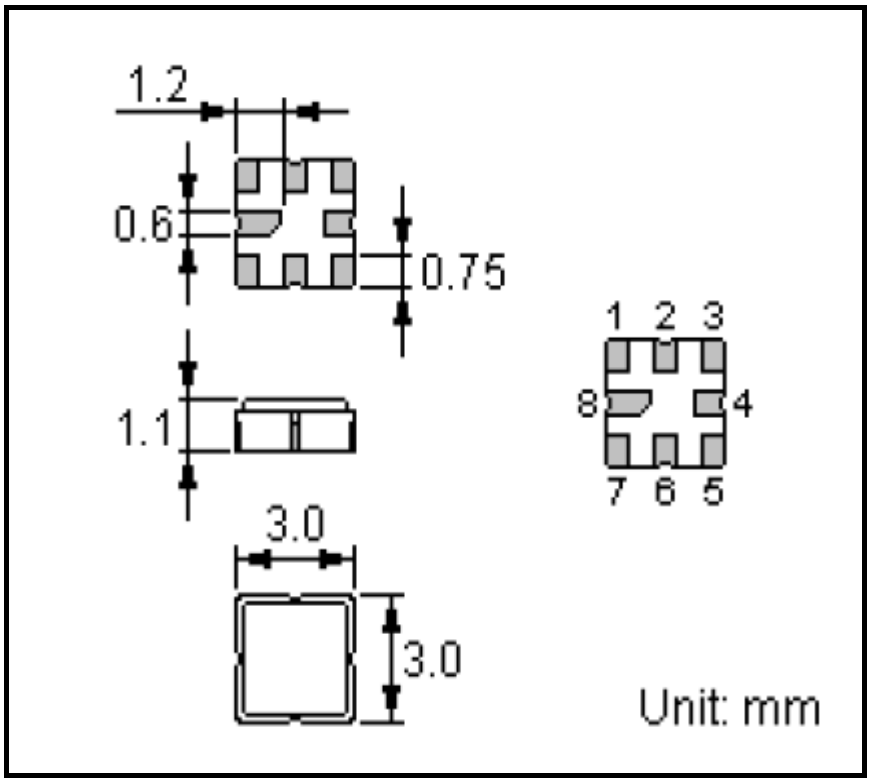
1. Electrical Specifications:

Characteristics		Unit	Minimum	Typical	Maximum
Center Frequency		MHz	-	800.00	-
Insertion Loss @ Fo		dB	-	14.00	15.00
1dB Bandwidth BW		MHz	125.00	135.0	-
Ultimate Attenuation	@ ±94.00MHz	dB	16.00	-	-
	@ ±100.00MHz		19.00	-	-
	@ ±107.00MHz		22.00	-	-
	@ ±115.00MHz		27.00	-	-
	@ ±125.00MHz		33.00	-	-
	@ ±138.00MHz		40.00	-	-
	@ ±219.00MHz		30.00	-	-
Group Delay Ripple		ns	-	-	80
Passband Ripple Fo @ ±62.5MHz		dB	-	0.5	1.0
Temperature Coefficient		ppm/°	-	-70	-
Operating Temperature Range		°C	-20 to +70		
Storage Temperature Range		°C	-40 to +85		
DC Voltage between any two pins		V	10		
Input Power Level		dBm	10		

2. Dimension:



Marking:
Too small for marking

Pin Configuration:

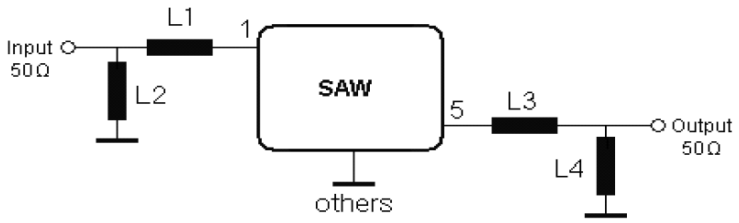
Input: 1

Output: 5

To be Grounded: 2, 3, 6, 7

Case Ground: 4, 8

Test Circuit



L1, L2, L3, L4 = TBD

Cautions:

1. **Static Voltage:**
   Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.
2. **Ultrasonic Cleaning:**
   Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.
3. **Soldering:**
   Only leads of component may be soldered. Please avoid soldering another part of component.

Environmental Characteristics	
High Temperature Exposure	**Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications.**
Low Temperature Exposure	**Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications.**
Temperature Cycling	**Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 minutes. Then release the device into the room conditions for 24 hours prior to the measurement. The device shall meet the specifications.**
Resistance to solder heat	**Dip the device terminal no closer than 1.5mm into the solder bath at 260°C ±10°C for 10±1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications.**
Solderability	**Subject the device terminals into the solder bath at 245°C ±5°C for 5s. More than 95% area of the terminals must be covered with new solder. It shall meet the specifications.**
Mechanical Shock	**Drop the device randomly onto the concrete floor from the height of 1 m 3 times. The device shall fulfill the specifications.**
Vibration	**Subject the device to the vibration for 1 hour each in x, y, and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications.**

3. Packing:

Dimensions

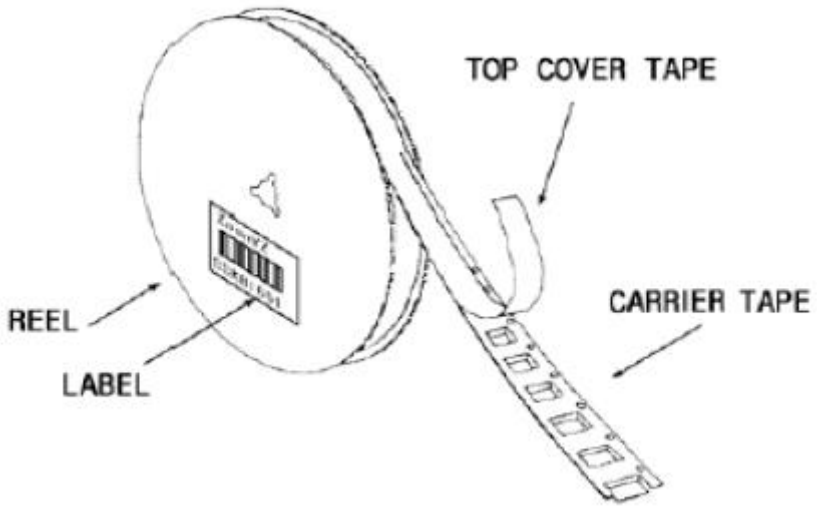
(1) Carrier Tape: Figure 1
(2) Reel: Figure 2
(3) The product shall be packed properly not to be damaged during transportation and storage.

Reeling Quantity

1000 pcs/reel 7”
3000 pcs/reel 13”

Taping Structure

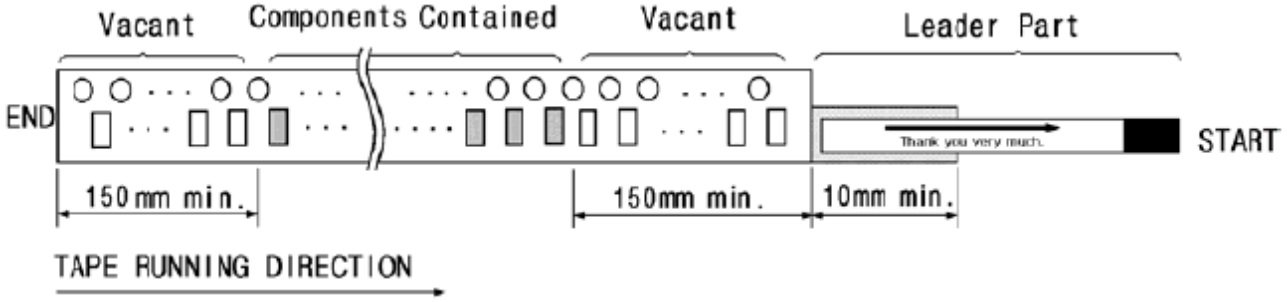
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



4. Tape Specifications:

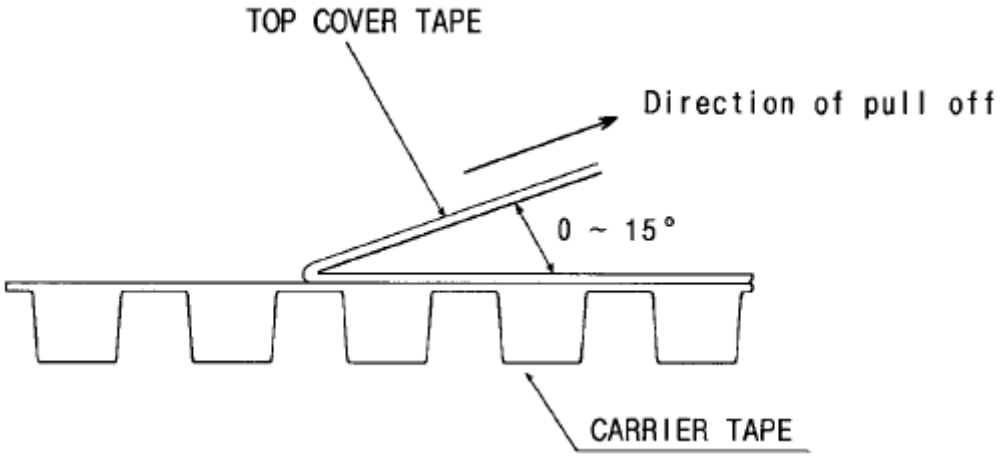
Tensile Strength of Carrier Tape: 4.4N/mm width

Top Cover Tape Adhesion (See the below figure)

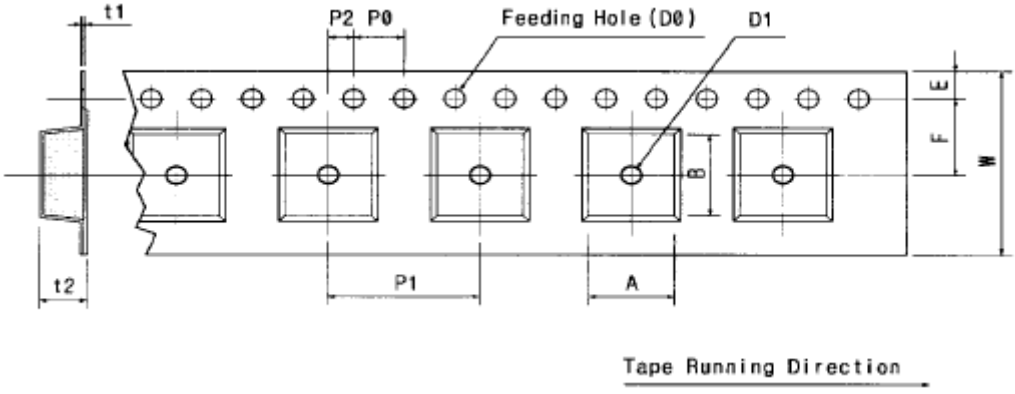
(1) pull off angle: 0~15°

(2) speed: 300mm/min.

(3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

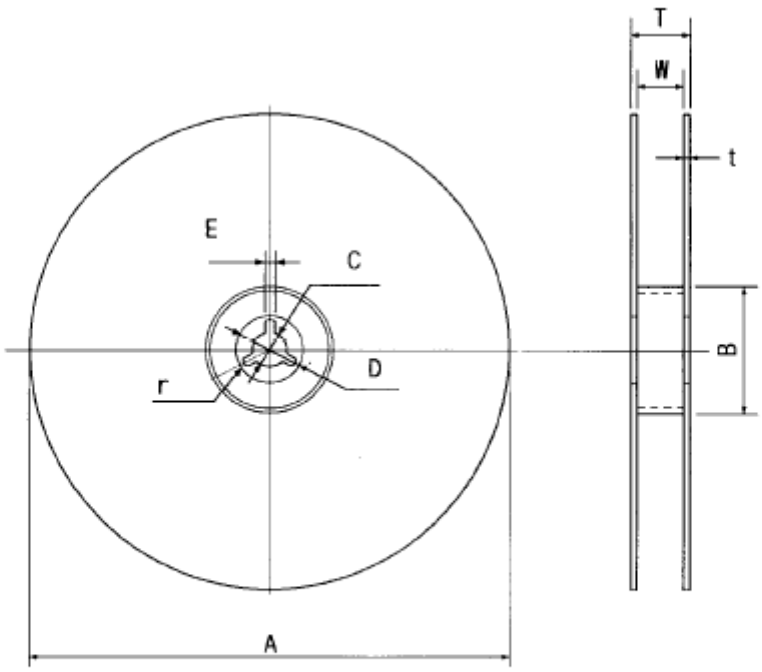


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00 ±0.30	5.50 ±0.10	1.75 ±0.10	4.00 ±0.10	4.00 ±0.10	2.00 ±0.10	Ø1.50	Ø1.5 ±0.25	0.31 ±0.05	1.30 ±0.10	3.4 MAX.	3.4 MAX

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330 ±1.0	Ø100 ±0.5	Ø13 ±0.5	Ø21 ±0.8	2 ±0.5	13 ±0.3	3 max.	1.0 max.